

# UCC2915, UCC3915 15-V PROGRAMMABLE HOT SWAP POWER MANAGER

SLUS198C - FEBUARY 2000 - REVISED - JUNE 2001

- Integrated 0.15-Ω Power MOSFET
- 7-V to 15-V Operation
- Digital-Programmable Current Limit from 0 A to 3 A
- 100-μA I<sub>CC</sub> When Disabled
- Programmable On Time
- Programmable Start Delay
- Fixed 2% Duty Cycle

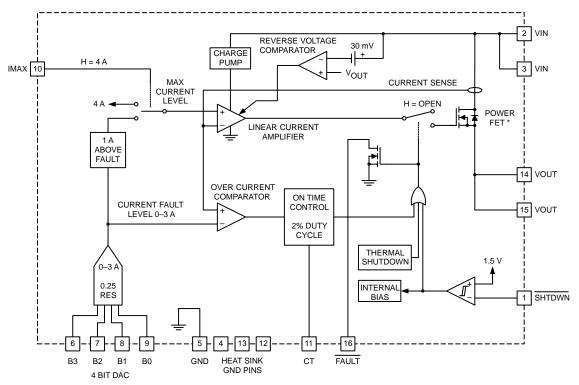
- Thermal Shutdown
- Fault-Output Indicator
- Maximum-Output Current Can Be Set to 1 A Above the Programmed-Fault Level or to a Full 4 A
- Power SOIC and TSSOP, Low Thermal Resistance Packaging

## description

The UCC3915 programmable hot swap power manager provides complete power-management, hot-swap capability, and circuit breaker functions. The only external component required to operate the device, other than power supply bypassing, is the fault-timing capacitor, C<sub>T</sub>. All control and housekeeping functions are integrated, and externally programmable. These include the fault current level, maximum output sourcing current, maximum fault time, and startup delay. In the event of a constant fault, the internal fixed 2% duty cycle ratio limits average output power.

The internal 4-bit DAC allows programming of the fault-level current from 0 A to 3 A with 0.25-A resolution. The IMAX control pin sets the maximum-sourcing current to 1 A above the trip level or to a full 4 A of output current for fast output capacitor charging. (continued)

## block diagram



NOTE: Pin numbers refer to DIL-16 and SOIC-16 packages.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2000, Texas Instruments Incorporated

UDG-99174

SLUS198C - FEBUARY 2000 - REVISED - JUNE 2001

## description (continued)

When the output current is below the fault level, the output MOSFET is switched on with a nominal ON resistance of 0.15  $\Omega$ . When the output current exceeds the fault level, but is less than the maximum-sourcing level, the output remains switched on, but the fault timer starts, charging CT. Once CT charges to a preset threshold, the switch is turned off, and remains off for 50 times the programmed fault time. When the output current reaches the maximum sourcing level, the MOSFET transitions from a switch to a constant current source.

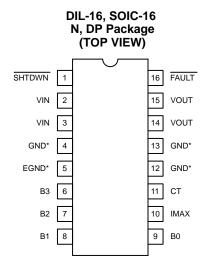
The UCC3915 can be put into sleep mode, drawing only 100  $\mu$ A of supply current. Other features include an open-drain fault-output indicator, thermal shutdown, undervoltage lockout, 7-V to 15-V operation, and low-thermal resistance SOIC and TSSOP power packages.

## absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

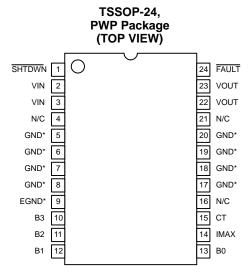
VIN	
VOUT – VIN	V
FAULT sink current	
FAULT voltage	0.3 V to 8 V
Output current	Self limiting
TTL input voltage	
Storage temperature, T <sub>stg</sub>	–65°C to 150°C
Junction temperature, TJ	–55°C to 150°C
Lead temperature (soldering, 10 sec.)	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## package information



\*Pin 5 serves as lowest impedance to the electrical ground; Pins 4, 12, and 13 serve as heat sink/ground. These pins should be connected to large etch areas to help dissipate heat. For N Package, pins 4, 12, and 13 are N/C.



\*Pin 9 serves as lowest impedance to the electrical ground; other GND pins serve as heat sink/ground. These pins should be connected to large etch areas to help dissipate heat.



<sup>‡</sup> Currents are positive into, negative out of the specified terminal. Consult Packaging Section of the *Interface Products Data Book* (TI Literature Number SLUD002) for thermal limitations and considerations of packages.

SLUS198C - FEBUARY 2000 - REVISED - JUNE 2001

electrical characteristics, these specifications apply for  $T_{\Delta}=-40^{\circ}\text{C}$  to 85°C for the UCC2915 and 0°C to 70°C for the UCC3915, VIN = 12 V, IMAX = 0.4 V, SHTDWN = 2.4 V,  $T_{A}=T_{J}$ , (unless otherwise stated)

## supply

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Voltage input range		7.0		15.0	V
Supply current			1.0	2.0	mA
Sleep mode current	SHTDWN = 0.2 V, no load		100	150	μΑ
Output leakage	SHTDWN = 0.2 V			20	μΑ

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

### output

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
	I <sub>OUT</sub> = 1 A (10 V to 12 V)		0.15	0.3	V
	I <sub>OUT</sub> = 2 A (10 V to 12 V)		0.3	0.6	V
	I <sub>OUT</sub> = 3 A (10 V to 12 V)		0.45	0.9	V
Voltage drop	I <sub>OUT</sub> = 1 A, VIN = 7 V and 15 V		0.2	0.4	V
	I <sub>OUT</sub> = 2 A, VIN = 7 V and 15 V		0.4	0.8	V
	I <sub>OUT</sub> = 3 A, VIN = 7 V, 12 V MAX		0.6	1.2	V
Initial startup time	See Note 2		100		μs
Short circuit response	See Note 2		100		ns
Thermal shutdown	See Note 2		165		°C
Thermal hysteresis	See Note 2		10		°C

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

### DAC

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
	Code = 0000-0011 (device off)				
	Code = 0100	0.07	0.25	0.45	Α
	Code = 0101	0.32	0.50	0.70	Α
	Code = 0110	0.50	0.75	0.98	Α
	Code = 0111	0.75	1.00	1.3	Α
Trip current	Code = 1000	1.0	1.25	1.6	Α
	Code = 1001	1.25	1.50	1.85	Α
	Code = 1010	1.5	1.75	2.15	Α
	Code = 1011	1.70	2.00	2.4	Α
	Code = 1100	1.90	2.25	2.7	Α
	Code = 1101	2.1	2.50	2.95	Α

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.



NOTE 2: Ensured by design. Not production tested.

SLUS198C - FEBUARY 2000 - REVISED - JUNE 2001

electrical characteristics, these specifications apply for  $T_A = -40^{\circ}$ C to 85°C for the UCC2915 and 0°C to 70°C for the UCC3915, VIN = 12 V, IMAX = 0.4 V, SHTDWN = 2.4 V,  $T_A = T_J$ , (unless otherwise stated)

## **DAC** (continued)

PARAMETER	TEST CONDITIONS		TYP	MAX	UNITS
Tita	Code = 1110	2.30	2.75	3.25	Α
Trip current	Code = 1111	2.50	3.0	3.50	Α
Max output current over trip (current source mode)	Code = 0100 to 1111, I <sub>MAX</sub> = 0 V	0.35	1.0	1.65	Α
Max output current (current source mode)	Code = 0100 to 1111, I <sub>MAX</sub> = 2.4 V	3.0	4.0	5.2	Α

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

#### fault timer

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
CT charge current	V <sub>CT</sub> = 1.0 V	-83	-62	-47	μΑ
CT discharge current	V <sub>CT</sub> = 1.0 V	0.8	1.2	1.8	μΑ
Output duty cycle	V <sub>OUT</sub> = 0 V	1.0%	1.9%	3.3%	
CT fault threshold		1.2	1.5	1.7	V
CT reset threshold		0.4	0.5	0.6	V

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

#### shutdown

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Shutdown threshold		1.1	1.5	1.9	V
Shutdown hysteresis			150		mV
Input current			100	500	nA

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

## open drain output (FAULT)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
High level output current	FAULT = 5 V			250	μΑ
Low level output voltage	I <sub>OUT</sub> = 5 mA		0.2	0.8	V

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.

### TTL input dc characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
TTL input voltage high		2.0			V
TTL input voltage low				0.8	V
TTL input high current	V <sub>IH</sub> = 2.4 V		3	10	μΑ
TTL input low current	V <sub>IL</sub> = 0.4 V			1	μΑ

NOTE 1: All voltages are with respect to GND. Current is positive into and negative out of the specified terminal.



## pin descriptions

**B0 – B3:** These pins provide digital input to the DAC, which sets the fault-current threshold. They can be used to provide a digital soft-start and adaptive-current limiting.

**CT:** A capacitor connected to ground sets the maximum-fault time. The maximum-fault time must be more than the time required to charge the external capacitance in one cycle. The maximum-fault time is defined as  $T_{FAULT} = 16.1 \times 10^3 \times C_T$ . Once the fault time is reached the output will shutdown for a time given by  $T_{SD} = 833 \times 10^3 \times C_T$ , this equates to a 1.9% duty cycle.

**FAULT:** Open-drain output, which pulls low upon any fault or interrupt condition, or thermal shutdown.

**IMAX:** When this pin is set to a logic low, the maximum-sourcing current will always be 1 A above the programmed-fault level. When set to a logic high, the maximum-sourcing current will be a constant 4 A for applications which require fast charging of load capacitance.

**SHTDWN**: When this pin is brought to a logic low, the IC is put into a sleep mode drawing typically less than 100  $\mu$ A of I<sub>CC</sub>. The input threshold is hysteretic, allowing the user to program a startup delay with an external RC circuit.

**VIN:** Input voltage to the UCC3915. The recommended voltage range is 7 V to 15 V. Both VIN pins should be connected together and connected to the power source.

**VOUT:** Output voltage from the UCC3915. Both VOUT pins should be connected together and connected to the load. When switched the output voltage will be approximately  $V_{IN}$  – (0.15  $\Omega \times I_{OUT}$ ). VOUT must not exceed VIN by greater than 0.3 V.

### **APPLICATION INFORMATION**

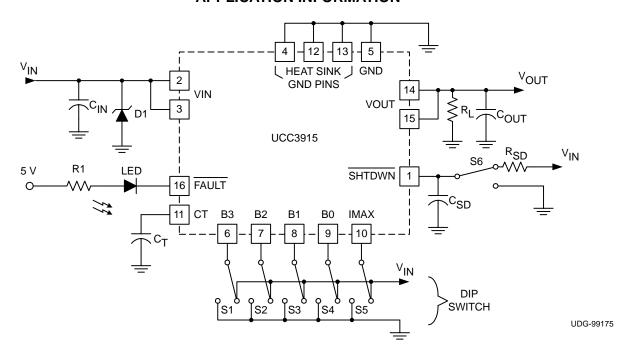


Figure 1. Evaluation Circuit

### **APPLICATION INFORMATION**

## protecting the UCC3915 from voltage transients

The parasitic inductance associated with the power distribution can cause a voltage spike at  $V_{IN}$  if the load current is suddenly interrupted by the UCC3915. It is important to limit the peak of this spike to less than 15 V to prevent damage to the UCC3915. This voltage spike can be minimized by:

- Reducing the power distribution inductance (e.g., twist the positive (+) and negative (-) leads of the power supply feeding V<sub>IN</sub>, locate the power supply close to the UCC3915 or use PCB power and ground planes).
- Decoupling V<sub>IN</sub> with a capacitor, C<sub>IN</sub> (refer to Figure 1), located close to the V<sub>IN</sub> pins. This capacitor is typically 1 μF or less to limit the inrush current.
- Clamping the voltage at V<sub>IN</sub> below 15 V with a Zener diode, D1(refer to Figure 1), located close to the V<sub>IN</sub> pins.

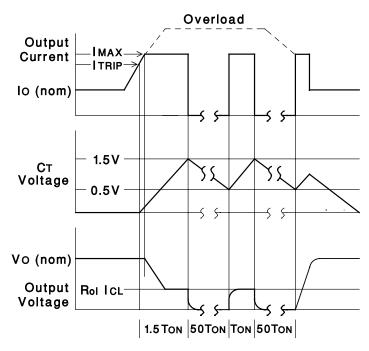


Figure 2. Load Current, Timing-Capacitor Voltage, and Output Voltage of the UCC3915 Under Fault Conditions

### estimating maximum load capacitance

For hot-swap applications, the rate at which the total output capacitance can be charged depends on the maximum-output current available and the nature of the load. For a constant-current, current-limited application, the output will come up if the load asks for less than the maximum available short-circuit current.

To ensure recovery of a duty cycle from a short-circuited load condition, there is a maximum total output capacitance which can be charged for a given unit on time (fault time). The design value of on or fault time can be adjusted by changing the timing capacitor  $C_T$ .



### **APPLICATION INFORMATION**

For worst-case constant-current load of value just less than the trip limit; C<sub>OUT(max)</sub> can be estimated from:

$$C_{OUT(max)} \approx \left(I_{MAX} - I_{LOAD}\right) \times \left(\frac{16.1 \times 10^3 \times C_T}{V_{OUT}}\right)$$

Where V<sub>OUT</sub> is the output voltage.

For a resistive load of value  $R_L$ , the value of  $C_{OUT(max)}$  can be estimated from:

$$C_{OUT(max)} \approx \left[ \frac{16.1 \times 10^{3} \times C_{T}}{R_{L} \times \ell n \left[ \frac{1}{1 - \frac{V_{OUT}}{MAX} \times R_{L}} \right]} \right]$$

Long  $C_T$  times must consider the maximum temperature. Thermal shutdown protection may be the limiting fault time.

## safety recommendations

Although the UCC3915 is designed to provide system protection for all fault conditions, all integrated circuits can ultimately fail short. For this reason, if the UCC3915 is intended for use in safety-critical applications where UL or some other safety rating is required, a redundant safety device such as a fuse should be placed in series with the device. The UCC3915 will prevent the fuse from blowing for virtually all fault conditions, increasing system reliability and reducing maintenance cost, in addition to providing the hot-swap benefits of the device.

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

. . ..

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

	Products		Applications	
Audio		www.ti.com/audio	Communications and Telecom	www.ti.com/communications
	Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
	Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
	DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
	DSP	dsp.ti.com	Industrial	www.ti.com/industrial
	Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
	Interface	interface.ti.com	Security	www.ti.com/security
	Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
	Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
	Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
	RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
	RF/IF and ZigBee® Solutions	www.ti.com/lprf		
		TI E2E Co	ommunity Home Page	e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated

- . .